

Abstract of the Invention

A near infrared-cutting material produced by forming, on a transparent substrate, a transparent resin film containing at least a near infrared absorbing-dye and a dye having a maximum absorption wavelength at 550
5 to 620 nm, wherein the amount of the solvent remaining in the transparent resin film is 5 ppm by weight to less than 500 ppm by weight; since the amount of the solvent remaining in the transparent resin film containing a near
10 infrared-absorbing dye, etc. is minimized, the long-term stability of the near infrared-absorbing dye, etc. in the film at high temperatures is greatly improved.